

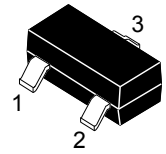


Features

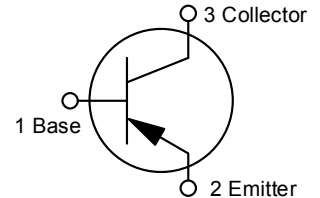
- RoHS Compliant and Halogen Free

Ordering Information

Device	Marking	Shipping
HMBT2907AXLT1G	2F	3000/Tape & Reel



SOT-23 (TO-236)



Maximum Ratings (T_A=25°C)

Parameter	Symbol	Limits	Units
Collector-Emitter Voltage	V _{CEO}	-60	Vdc
Collector-Base Voltage	V _{CBO}	-60	Vdc
Emitter-Base Voltage	V _{EBO}	-5	Vdc
Collector Current-Continuous	I _c	-600	mAdc

Thermal Characteristics

Parameter	Symbol	Limits	Units
Total Device Dissipation FR-5 Board* ¹ , T _A =25°C	P _D	225	mW
Total Device Dissipation, Derate above 25°C	P _D	1.8	mW/°C
Thermal Resistance, Junction to Ambient* ¹	R _{θJA}	556	°C/W
Junction and Storage Temperature	T _J , T _{stg}	-55 to +150	°C

*1 FR-5=1.0x0.75x0.062 in.



Electrical Characteristics ($T_A=25^\circ\text{C}$)

Off Characteristics

Characteristic	Symbol	Min.	Typ.	Max.	Unit
Collector-Emitter Breakdown Voltage ($I_C=-10\text{mA}$, $I_B=0$)	$V_{(BR)CEO}$	-60	-	-	V
Collector-Base Breakdown Voltage ($I_C=-10\mu\text{A}$, $I_E=0$)	$V_{(BR)CBO}$	-60	-	-	V
Emitter-Base Breakdown Voltage ($I_E=-10\mu\text{A}$, $I_C=0$)	$V_{(BR)EBO}$	-5	-	-	V
Collector Cutoff Current ($V_{CB}=-30\text{Vdc}$, $V_{EB(off)}=-5.0\text{Vdc}$)	I_{CEX}	-	-	-10	nA
Collector Cutoff Current ($V_{CB}=-50\text{V}$, $I_E=0$)	I_{CBO}	-	-	-0.01	μA
Collector Cutoff Current ($V_{CB}=-50\text{V}$, $I_E=0$, $T_A=125^\circ\text{C}$)	I_{CBO}	-	-	-10	μA
Base Cutoff Current ($V_{CE}=-30\text{Vdc}$, $V_{EB(off)}=-0.5\text{Vdc}$)	I_{BL}	-	-	-50	nA

On Characteristics*²

Characteristic	Symbol	Min.	Typ.	Max.	Unit
DC Current Gain ($I_C=-0.1\text{mA}$, $V_{CE}=-10\text{Vdc}$)	hFE	75	-	-	-
DC Current Gain ($I_C=-1.0\text{mA}$, $V_{CE}=-10\text{Vdc}$)	hFE	100	-	-	-
DC Current Gain ($I_C=-10\text{mA}$, $V_{CE}=-10\text{Vdc}$)	hFE	100	-	-	-
DC Current Gain ($I_C=-150\text{mA}$, $V_{CE}=-10\text{Vdc}$)	hFE	100	-	300	-
DC Current Gain ($I_C=-500\text{mA}$, $V_{CE}=-10\text{Vdc}$)	hFE	50	-	-	-
Collector-Emitter Saturation Voltage ($I_C=-150\text{mA}$, $I_B=-15\text{mA}$)	$V_{CE(sat)}$	-	-	-0.4	V
Collector-Emitter Saturation Voltage ($I_C=-500\text{mA}$, $I_B=-50\text{mA}$)	$V_{CE(sat)}$	-	-	-1.6	V
Base-Emitter Saturation Voltage ($I_C=-150\text{mA}$, $I_B=-15\text{mA}$)	$V_{BE(sat)}$	-	-	-1.3	V
Base-Emitter Saturation Voltage ($I_C=-500\text{mA}$, $I_B=-50\text{mA}$)	$V_{BE(sat)}$	-	-	-2.2	V

Small Signal Characteristics

Characteristic	Symbol	Min.	Typ.	Max.	Unit
Current Gain Bandwidth Product ($I_C=-50\text{mA}$, $V_{CE}=-20\text{Vdc}$, $f=100\text{MHz}$)	f_T	200	-	-	MHz
Output Capacitance ($V_{CB}=-10\text{Vdc}$, $I_E=0$, $f=1.0\text{MHz}$)	C_{obo}	-	-	8	pF
Input Capacitance ($V_{EB}=-2\text{Vdc}$, $I_C=0$, $f=1.0\text{MHz}$)	C_{ibo}	-	-	30	pF

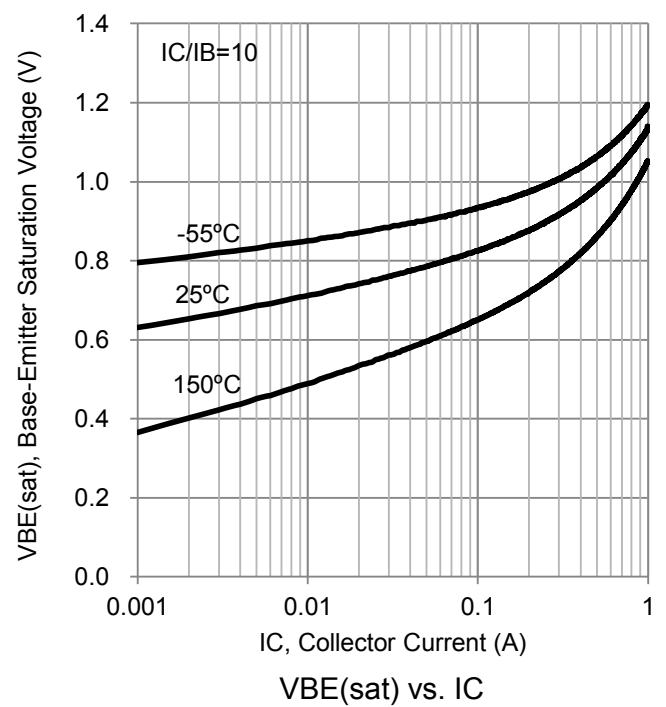
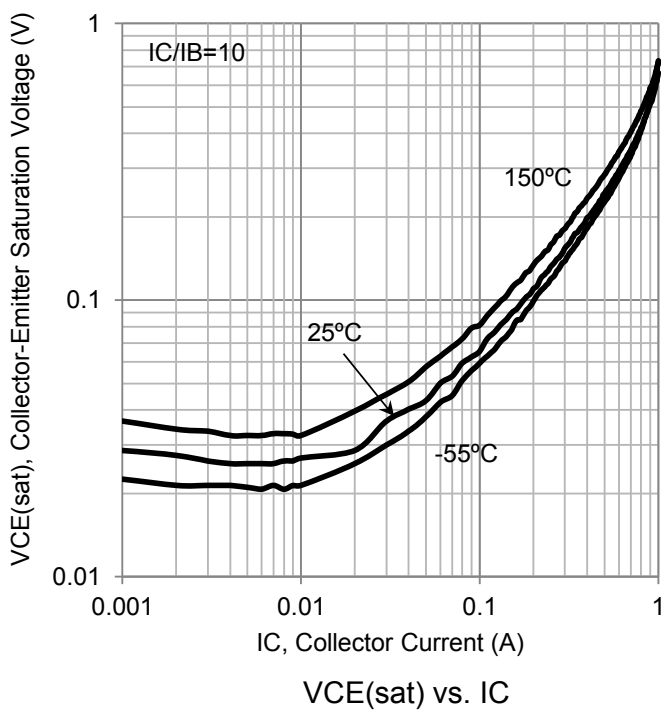
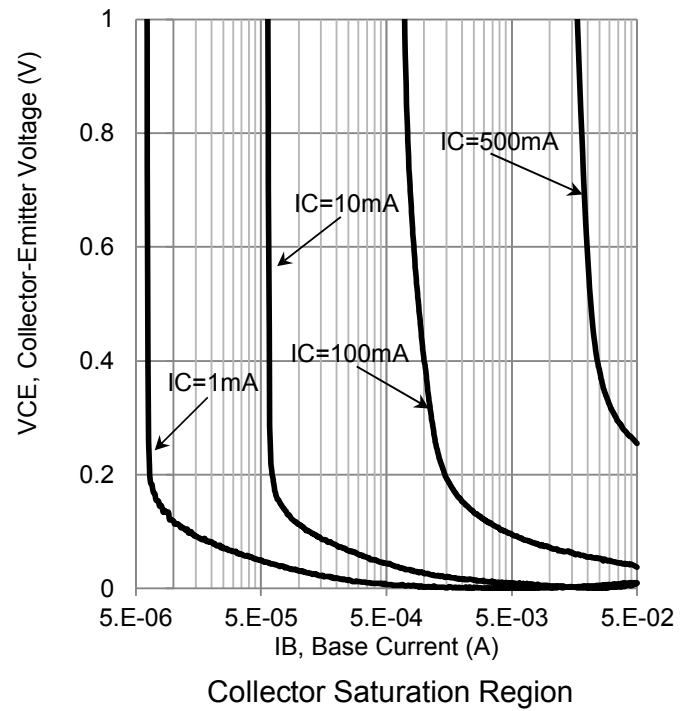
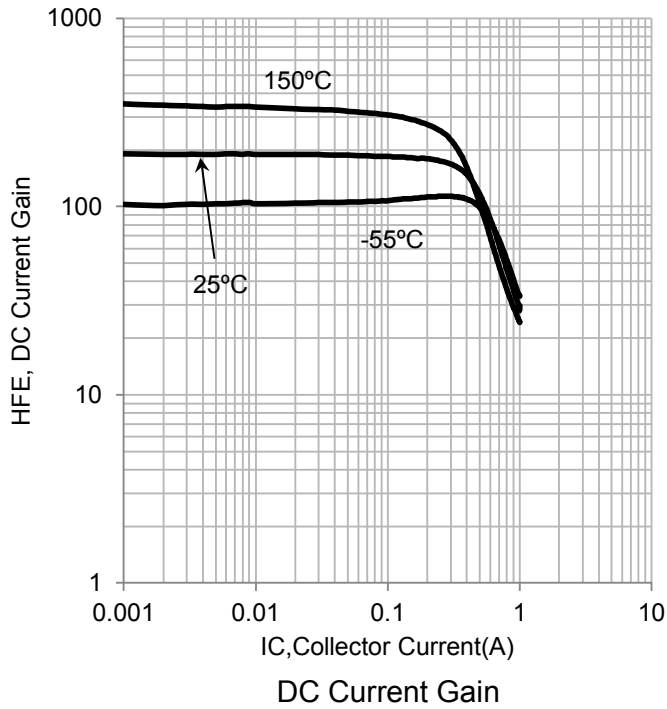
Switching Characteristics

Characteristic	Symbol	Min.	Typ.	Max.	Unit
Turn-On Time ($V_{CC}=-30\text{Vdc}$, $I_C=-150\text{mA}$, $I_{B1}=-15\text{mA}$)	t_{on}	-	-	45	ns
Delay Time ($V_{CC}=-30\text{Vdc}$, $I_C=-150\text{mA}$, $I_{B1}=-15\text{mA}$)	t_d	-	-	10	ns
Rise Time ($V_{CC}=-30\text{Vdc}$, $I_C=-150\text{mA}$, $I_{B1}=-15\text{mA}$)	t_r	-	-	40	ns
Storage Time ($V_{CC}=-6\text{Vdc}$, $I_C=-150\text{mA}$, $I_{B1}=I_{B2}=-15\text{mA}$)	t_s	-	-	225	ns
Fall Time ($V_{CC}=-6\text{Vdc}$, $I_C=-150\text{mA}$, $I_{B1}=I_{B2}=-15\text{mA}$)	t_f	-	-	60	ns
Turn-Off Time ($V_{CC}=-6\text{Vdc}$, $I_C=-150\text{mA}$, $I_{B1}=I_{B2}=-15\text{mA}$)	t_{off}	-	-	280	ns

*2 Pulse Test: Pulse Width \leq 300 μs , Duty Cycles \leq 2.0%

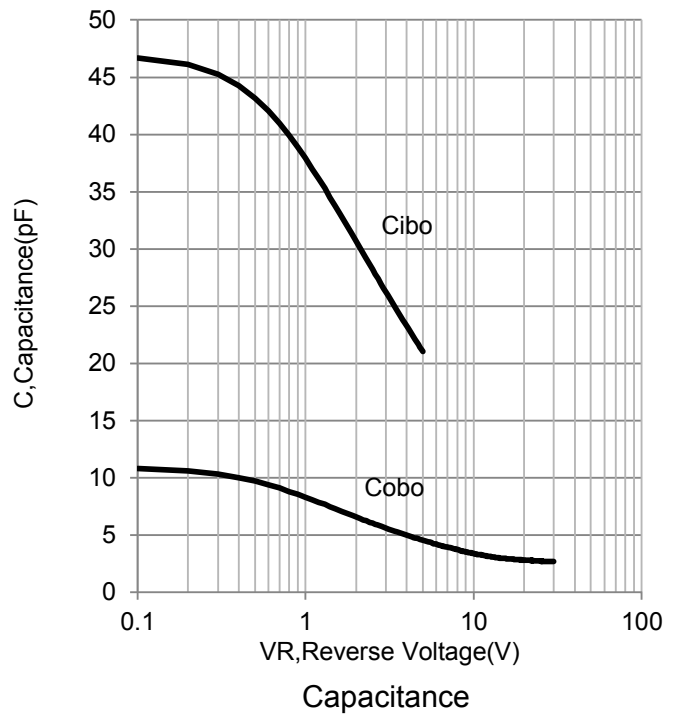
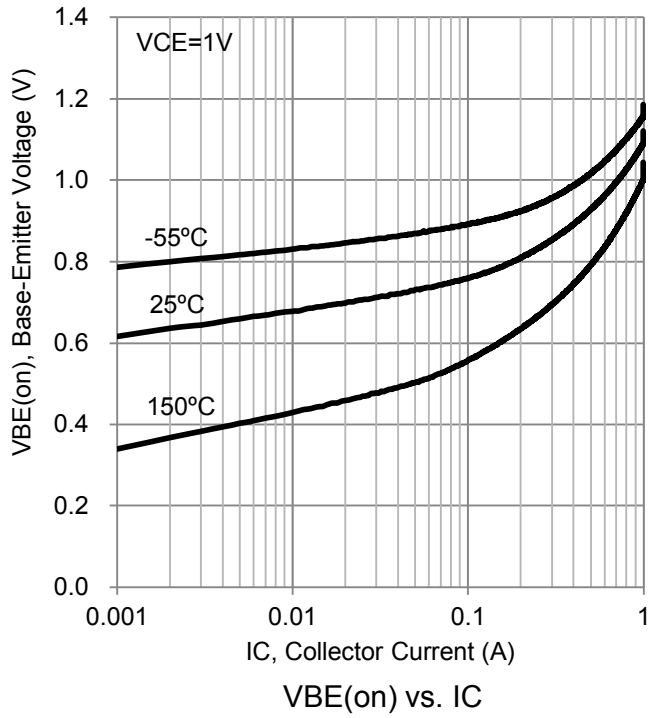


Electrical Characteristics Curves



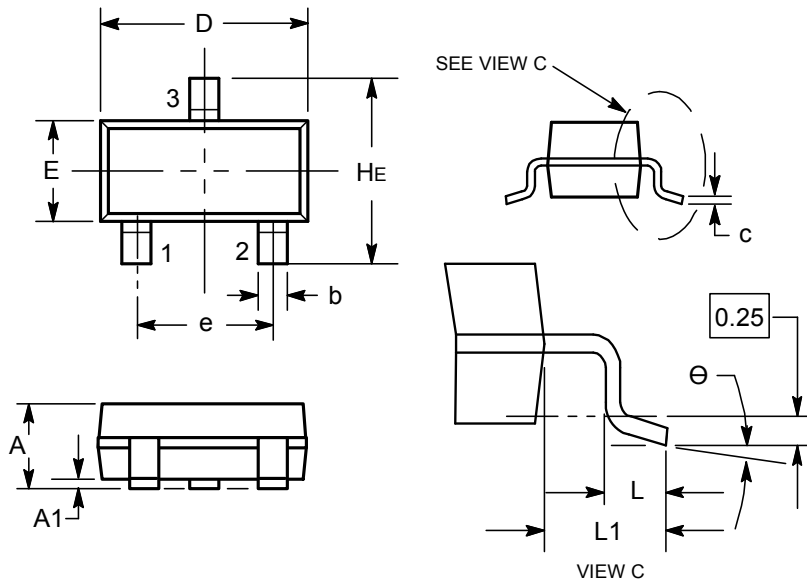


Electrical Characteristics Curves





Package Dimension



DIM	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	0.89	1	1.11	0.035	0.04	0.044
A1	0.01	0.06	0.1	0.001	0.002	0.004
b	0.37	0.44	0.5	0.015	0.018	0.02
c	0.09	0.13	0.18	0.003	0.005	0.007
D	2.80	2.9	3.04	0.11	0.114	0.12
E	1.20	1.3	1.4	0.047	0.051	0.055
e	1.78	1.9	2.04	0.07	0.075	0.081
L	0.10	0.2	0.3	0.004	0.008	0.012
L1	0.35	0.54	0.69	0.014	0.021	0.029
HE	2.10	2.4	2.64	0.083	0.094	0.104
θ	0°	-	10°	0°	-	10°

Notes:

1. Dimensioning and tolerancing per ansi Y14.5m, 1982.
2. Controlling Dimension: Millimeter.
3. Maximum lead thickness includes lead finish. Minimum lead thickness is the minimum thickness of base material.
4. Dimensions d and e do not include mold flash, protrusions or gate burrs.

Soldering Footprint

